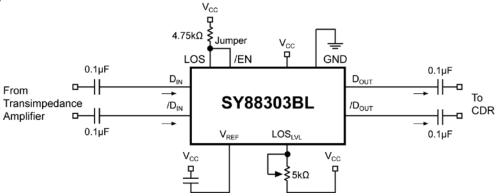
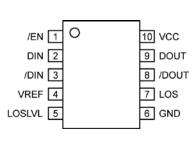
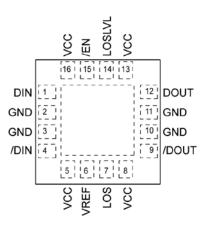
Typical Application



Pin Configuration



10-Pin EPAD-MSOP (K10-2)



16-Pin QFN

Ordering Information

Part Number	Package Type	Operating Range	Package Marking	Lead Finish	
SY88303BLEY	K10-2	Industrial	303B with Pb-Free bar line indicator	Matte-Sn Pb-free	
SY88303BLEYTR ⁽¹⁾	K10-2	Industrial	303B with Pb-Free bar line indicator	Matte-Sn Pb-free	
SY88303BLMG	QFN-16	Industrial	303B with Pb-Free bar line indicator	NiPdAu Pb-free	
SY88303BLMGTR ⁽¹⁾	QFN-16	Industrial	303B with Pb-Free bar line indicator	NiPdAu Pb-free	

Note:

1. Tape and Reel.

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Pin Description

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Pin Number (MSOP)	Pin Number (QFN)	Pin Name	Туре	Pin Function
1	15	/EN	TTL Input: Default is low.	Enable bar: De-asserts true data output when High.
2	1	DIN	Data Input	True data input with 50Ω termination to V_{REF} .
3	4	/DIN	Data Input	Complementary data input w50 Ω termination to V_{REF} .
4	6	VREF		Reference Voltage: Placing a capacitor here to V _{CC} helps stabilize.
5	14	LOSLVL	Input	Loss-of-Signal Level Set: A resistor from this pin to V_{CC} sets the threshold for the data input amplitude at which the LOS output will be asserted.
6 Exposed Pad	2, 3, 10, 11 Exposed Pad	GND	Ground	Device ground. Exposed pad must be connected to PCB ground plane.
7	7	100	LOS Open Collector TTL Output	Loss-of-Signal: Asserts high when the data input amplitude falls below the threshold sets by LOS _{LVL} .
		LOS		For proper operation, install an external 4.75k Ω pull-up resistor at this output.
8	9	/DOUT	CML Output	Complementary data output.
9	12	DOUT	CML Output	True data output.
10	5, 8, 13, 16	VCC	Power Supply	Positive power supply.

Absolute Maximum Ratings(1)

Supply Voltage (V _{CC})	0V to +4.0V
Input Voltage (DIN, DIN)	0 to V _{CC}
Output Current (I _{OUT})	
Continuous	<u>+</u> 50mA
Surge	<u>+</u> 100mA
/EN Voltage	0 to V _{CC}
V _{REF} Current	800µA to +500µA
LOS _{LVL} Voltage	V_{REF} to V_{CC}
Lead Temperature (soldering, 20se	c.) 260°C
Storage Temperature (T _s)	65°C to +150°C

Operating Ratings⁽²⁾

Supply Voltage (V _{CC})	+3 0V to +3 6V
Ambient Temperature (T _A)	
Junction Temperature (T _J) Junction Thermal Resistance ⁽³⁾	
EPAD-MSOP	
θ_{JA} (Still-Air)	38°CW
ΨЈВ	22°CW
QFN	
θ _{JA} (Still-Air)	61°CW
M in	38°CW

DC Electrical Characteristics

 $V_{CC}=3.0V~to~3.6V;~R_L=50\Omega~to~V_{CC};~T_A=-40^{\circ}C~to~+85^{\circ}C;~typical~values~at~V_{CC}=3.3V,~T_A=25^{\circ}C.$

Symbol	Parameter	Condition	Min	Тур	Max	Units
Icc	Power Supply Current	No output load		38	60	mA
V _{LOSLVL}	LOS _{LVL} Voltage		V_{REF}		V _{CC}	V
V _{OH}	CML Output HIGH Voltage		V _{CC} -0.020	V _{CC} -0.005	Vcc	V
V _{OL}	CML Output LOW Voltage		V _{CC} -0.475	V _{CC} -0.4	V _{CC} -0.350	V
V _{OFFSET}	Differential Output Offset				<u>+</u> 80	mV
V_{REF}	Reference Voltage		V _{CC} -1.48	V _{CC} -1.32	V _{CC} -1.16	V
Zı	Single-Ended Input Impedance		40	50	60	Ω

TTL DC Electrical Characteristics

 $V_{CC} = 3.0V$ to 3.6V; $T_A = -40$ °C to +85°C.

Symbol	Parameter	Condition	Min	Тур	Max	Units
V _{IH}	/EN Input HIGH Voltage		2.0			V
V _{IL}	/EN Input LOW Voltage				0.8	V
I _{IH}	/EN Input HIGH Current	V _{IN} = 2.7V			20	μA
		$V_{IN} = V_{CC}$			100	μΑ
I _{IL}	/EN Input LOW Current	V _{IN} = 0.5V	-300			μA
I _{OH}	LOS Output Leakage	V _{OH} = 3.6V			100	μA
V _{OL}	LOS Output LOW Level	$I_{OL} = +4mA$			0.5	V

Notes:

- Permanent device damage may occur if absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.
- 2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
- Thermal performance assumes the use of a 4-layer PCB. Exposed pad must be soldered (or equivalent) to the device's most negative potential on the PCB.

AC Electrical Characteristics

 V_{CC} = 3.0V to 3.6V; R_L = 50 Ω to V_{CC} ; T_A = -40°C to +85°C; typical values at V_{CC} = 3.3V, T_A = +25°C.

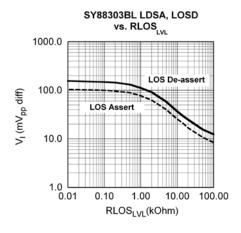
Symbol	Parameter	Condition	Min	Тур	Max	Units
t _r , t _f	Output Rise/Fall Time (20% to 80%)	Note 4		60	120	ps
t _{JITTER}	Deterministic	Note 5		15		ps _{PP}
	Random	Note 6		5		ps _{RMS}
V_{ID}	Differential Input Voltage Swing	Figure 1	10		1800	mV_{PP}
V _{OD}	Differential Output Voltage Swing	V _{ID} ≥ 12mV _{PP} , Figure 1	700	800	950	mV_{PP}
T _{OFF}	LOS De-assert Time			2	10	μs
T _{ON}	LOS Assert Time			2	10	μs
LOS _{DL}	Low LOS De-assert Level	R = $15k\Omega$, Note 8		27		mV_{PP}
LOS _{AL}	Low LOS Assert Level	$R = 15k\Omega$, Note 8		18		mV_{PP}
HYSL	Low LOS Hysteresis	$R = 15k\Omega$, Note 7		3.4		dB
LOS _{DM}	Medium LOS De-assert Level	R = 5kΩ, Note 8		53	80	mV_{PP}
LOS _{AM}	Medium LOS Assert Level	R = 5kΩ, Note 8	21	36		mV_{PP}
HYS _M	LOS Hysteresis	$R = 5k\Omega$, Note 7	2	3.5	6	dB
LOS _{DH}	High LOS De-assert Level	R = 100Ω, Note 8		137	200	mV_{PP}
LOS _{AH}	High LOS Assert Level	R = 100Ω, Note 8	70	94		mV_{PP}
HYS _H	High LOS Hysteresis	R = 100Ω, Note 7	2	3.5	6	dB
B _{-3dB}	3dB Bandwidth			2		GHz
$A_{V(Diff)}$	Differential Voltage Gain			39		dB
S ₂₁	Single-ended Small-Signal Gain		26	33		dB

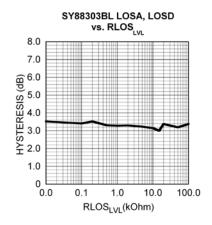
Notes:

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- 4. Amplifier in limiting mode. Input is a 200MHz, 100mV_{PP} square wave.
- 5. Deterministic jitter measured using 3.2Gbps K28.5 pattern, $V_{ID} = 10 \text{mV}_{PP}$.
- 6. Random jitter measured using 3.2Gbps K28.7 pattern, $V_{ID} = 10 \text{mV}_{PP}$.
- 7. This specification defines electrical hysteresis as 20log (LOS De-assert/LOS Assert). The ratio between optical hysteresis and electrical hysteresis is found to vary between 1.5 and 2, depending upon the level of received optical power and ROSA characteristics. Based upon that ratio, the optical hysteresis corresponding to the electrical hysteresis range 2dB-6dB, shown in the AC characteristics table, will be 1dB-3dB Optical Hysteresis.
- 8. See "Typical Operating Characteristics" for a graph showing how to choose a particular R_{LOSLVL} for a particular LOS assert and its associated de-assert amplitude.

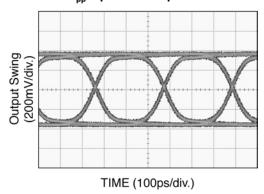
Typical Operating Characteristics



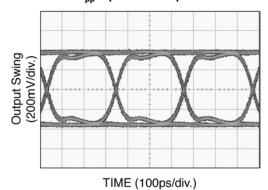


Functional Characteristics

20mV_{pp} Input @3.2Gbps 2²³-1 PRBS

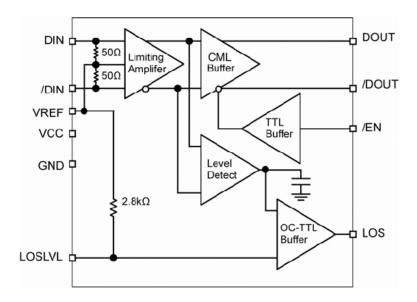


1800mV_{pp} Input @3.2Gbps 2²³-1 PRBS



6

Functional Block Diagram



Detailed Description

The SY88303BL low-power limiting post amplifiers operate from a single +3.3V power supply, over temperatures from -40°C to +85°C. Signals with data rates up to 3.2Gbps and as small as 10°MV_{PP} can be amplified. Figure 1 shows the allowed input voltage swing. The SY88303BL generates a LOS output allowing feedback to /EN for output stability. LOS_{LVL} sets the sensitivity of the input amplitude detection.

Input Amplifier Buffer

Figure 2 shows a simplified schematic of the input stage. The high-sensitivity of the input amplifier allows signals as small as 10mV_{PP} to be amplified. The input amplifier also allows input signals as large as 1800mV_{PP}. Input signals below 12mVpp are linearly amplified with a typical 42dB differential voltage gain. Since it is a limiting amplifier, these devices output typically 800mV_{PP} voltage-limited waveforms for input signals greater than 12mV_{PP}. Applications requiring the SY88303BL to operate with strong signals should have the upstream TIA placed as close as possible to the devices' input pins. This ensures the best performance of the device.

Output Buffer

The SY88303BL CML output buffers are designed to drive 50Ω lines. The output buffer requires appropriate termination for proper operation. An exter Ω al 50 resistor to V_{CC} for each output pin provides this. Figure 3 shows a simplified schematic of the output stage.

Loss-of-Signal

The SY88303BL generates a chatter-free LOS open-collector TTL output, as shown in Figure 4. LOS is used to determine that the input amplitude is large enough to be considered a valid input. LOS asserts high if the input amplitude falls below the threshold sets by LOS_{LVL} and de-asserts low otherwise. LOS can be fed back to the enable bar (/EN) input to maintain output stability under a loss-of-signal condition. /EN de-asserts the true output signal without removing the input signals.

Loss-of-Signal Level Set

Programmable LOS level-set pin (LOS_{LVL}) sets the threshold of the input amplitude detection. Connecting an external resistor between $V_{\rm CC}$ and LOS_{LVL} set the voltage at LOS_{LVL}. This voltage ranges from $V_{\rm CC}$ to $V_{\rm REF}$. The external resistor creates a voltage divider between $V_{\rm CC}$ and $V_{\rm REF}$, as shown in Figure 5.

Hysteresis

The SY88303BL typically provides 3.5dB LOS electrical hysteresis. By definition, a power ratio measured in dB is 10log (power ratio). Power is calculated as $V^2_{\rm IN}/R$ for an electrical signal. Hence, the same ratio can be stated as 20log (voltage ratio). While in linear mode, the electrical voltage input changes linearly with the optical power and therefore, the ratios change linearly. Thus, the optical hysteresis in dB is half the electrical hysteresis in dB given in the data sheet. Since the SY88303BL is an electrical device, this data sheet refers to hysteresis in electrical terms. With 3.5dB LOS hysteresis, a voltage factor of 1.5 is required to assert or de-assert LOS.

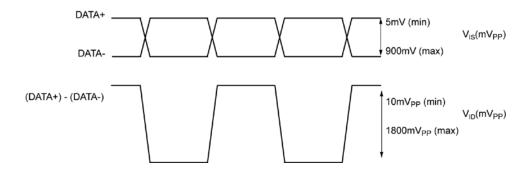
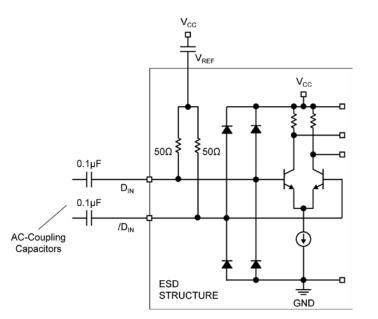


Figure 1. V_{IS} and V_{ID}

8



 V_{CC} V_{CC} V

Figure 2. Input Structure

Figure 3. Output Structure

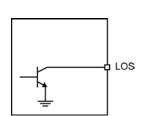


Figure 4. LOS Output Structure

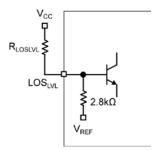
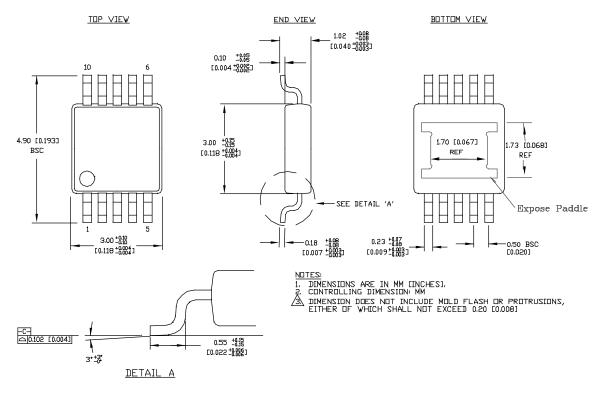
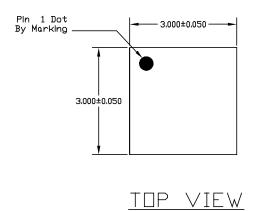


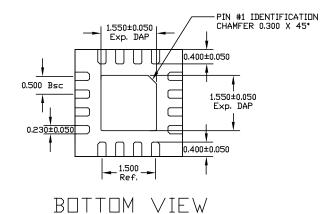
Figure 5. LOS $_{\rm LVL}$ Setting Circuit

Package Information



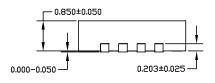
10-Pin EPAD-MSOP (K10-2)





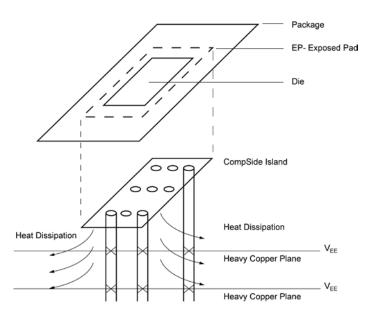
- NOTE:

 1. ALL DIMENSIONS ARE IN MILLIMETERS.
 2. MAX. PACKAGE WARPAGE IS 0.05 mm.
 3. MAXIMUM ALLOWABE BURRS IS 0.076 mm IN ALL DIRECTIONS.
 4. PIN #1 ID ON TOP WILL BE LASER/INK MARKED.





16-Pin QFN



PCB Thermal Consideration for 16-Pin QFN® Package (Always solder, or equivalent, the exposed pad to the PCB)

Package Notes:

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- Package meets Level 2 qualification.
- 2. All parts are dry-packaged before shipment.
- Exposed pad must be soldered to a ground for proper thermal management, solder void has to be less than 50% of the epad area.

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